

## 65N06-VB TO220F Datasheet

# N-Channel 60-V (D-S) MOSFET

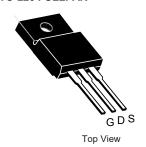
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>		
60	0.010 at V <sub>GS</sub> = 10 V	70		
60	0.012 at V <sub>GS</sub> = 4.5 V	55		

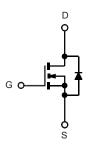
#### **FEATURES**

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:









N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25	°C, unless other	wise noted)		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V <sub>GS</sub>	± 20	V
Continuous Dusin Comment /T = 475 °C\h	T <sub>C</sub> = 25 °C	I <sub>D</sub>	70	
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 100 °C	] 'D	50ª	] 
Pulsed Drain Current		I <sub>DM</sub>	200	A
Continuous Source Current (Diode Conduction)		Is	50ª	
Avalanche Current		I <sub>AS</sub>	50	1
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ
Mandanana Danasa Birada attan	T <sub>C</sub> = 25 °C	P <sub>D</sub>	136	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		3 <sup>b</sup> , 8.3 <sup>b, c</sup>	] vv
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Marian and Long-Marian As Analysis and	t ≤ 10 sec	R <sub>thJA</sub>	15	18			
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	<b>T</b> thJA	40	50	°C/W		
Maximum Junction-to-Case		R <sub>thJC</sub>	0.85	1.1			

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c.  $t \le 10 \text{ s}$ .

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Parameter	Symbol	Test Conditions	Min.	Typ.a	Max.	Unit	
Static					'		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu A$	60			\/	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2	3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		50		μΑ	
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250	•	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	60			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.010			
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.016		1	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.020		μА	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		0.012			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S	
Dynamic					 		
Input Capacitance	C <sub>iss</sub>			2650			
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		470		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			225			
Total Gate Charge <sup>c</sup>	Qg			47	70		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		10		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			12			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_{L}$ = 0.6 $\Omega$ $I_{D} \cong$ 50 A, $V_{GEN}$ = 10 V, $R_{g}$ = 2.5 $\Omega$		15	25		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			35	50	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				70	Α	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		1	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs		45	100	ns	

#### Notes:

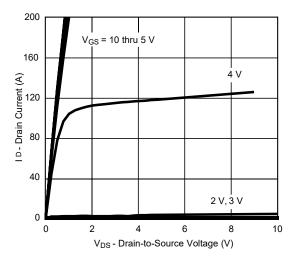
- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq 300~\mu s$ , duty cycle  $\leq 2~\%$ .
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

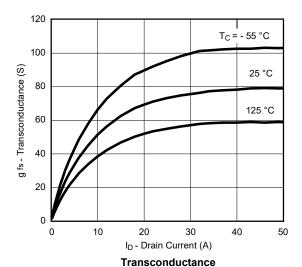
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### TYPICAL CHARACTERISTICS (25 °C unless noted)



#### **Output Characteristics**



C - Capacitance (pF) 2500 2000 1500 1000  $\mathsf{C}_{\mathsf{oss}}$ 500  $C_{\rm rss}$ 

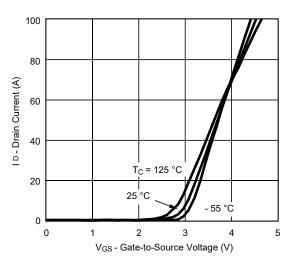
20

 $\overline{C_{iss}}$ 

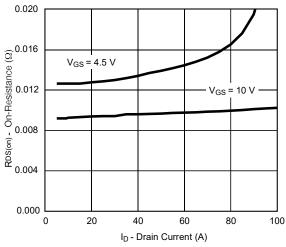
V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance

30

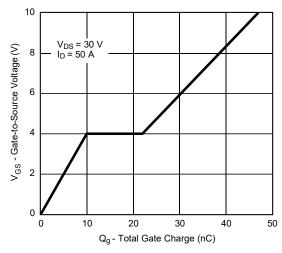
60



#### **Transfer Characteristics**



On-Resistance vs. Drain Current



**Gate Charge** 

10

4000 3500

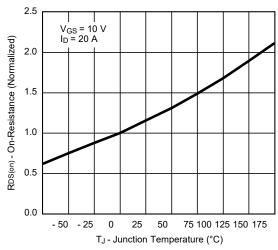
3000

0

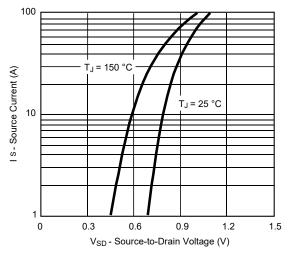
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## TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

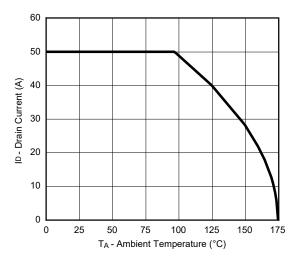


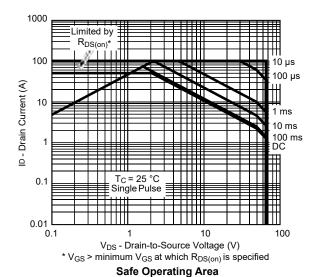
Source-Drain Diode Forward Voltage

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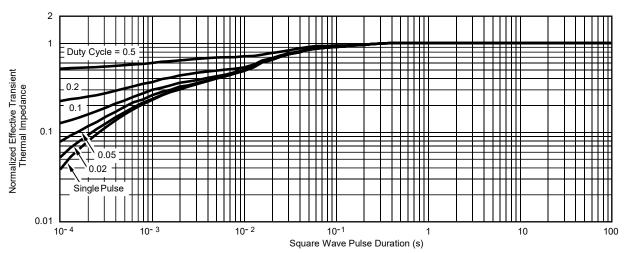


#### THERMAL RATINGS





Maximum Drain Current vs. Ambient Temperature



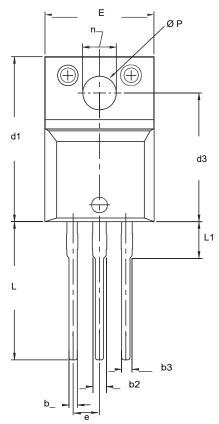
Normalized Thermal Transient Impedance, Junction-to-Case

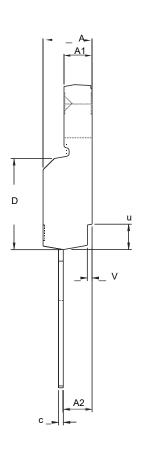
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## **TO-220 FULLPAK (HIGH VOLTAGE)**





	MILLI	METERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
A	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	2.54 BSC		0.100 BSC	
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØΡ	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
٧	0.400	0.500	0.016	0.020	

DWG: 5972

#### Notes

- To be used only for process drawing.
  These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
  All critical dimensions should C meet C<sub>pk</sub> > 1.33.
  All dimensions include burns and plating thickness.

- 5. No chipping or package damage.

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